

DDR4 DIMM

TE Internal #: 2309410-2 SO DIMM Sockets, Small Outline (SO), Stack Height .205 in [5.2 mm], Right Angle Module Orientation, 200 / 260 Position, DDR4 DIMM

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DRAM Type: Small Outline (SO) Stack Height: 5.2 mm [.205 in] Module Orientation: Right Angle Connector System: Cable-to-Board Number of Positions: 200, 260

All DDR4 SO DIMM Sockets (39)

Features

Product Type Features

DRAM Type

Connector System	Cable-to-Board
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of Keys	1
Number of Rows	2
Module Orientation	Right Angle
Number of Positions	200, 260
Electrical Characteristics	
DRAM Voltage	1.2 V
Signal Characteristics	
SGRAM Voltage	1.2 V
Body Features	
Ejector Location	Both Ends
Retention Post Material	Copper Alloy

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SO DIMM Sockets, Small Outline (SO), Stack Height .205 in [5.2 mm], Right Angle Module Orientation, 200 / 260 Position, DDR4 DIMM



Latch Matsail High Lamparature Thempoplastic Retention Post Location Both Ends Fjector Type Locking Connector Profile Low Connector Profile Low Connector Profile Low Connector Profile Low Connector Profile Memory Card Connect Underplating Material Nickel PEB Contact Termination Area Plating Material Cold Plash Connect Mating Area Plating Material Gold Connect Mating Area Plating Material Gold Connect Mating Area Plating Material Gold Connect Mating Area Plating Material Thickness .127 µm(5 µm) Connect Current Rating (Max) .5 A Termination Features Surface Mounti PCE Mounting Style Surface Mounti PCE Mounting Style Surface Mounti PCE Mount Retention With PCE Mount Retention Type Solder Pog Connector Mounting Type Board Mount PCE Mount Retention Type Solder Pog Connector Mounting Type Board Mount <t< th=""><th></th><th>·</th></t<>		·
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Connector Mounting TypeBoard MountHousing FeaturesHigh Temperature ThermoplasticHousing MaterialHigh Temperature ThermoplasticHousing ColorBlackCenterline (Pitch).5 mm[.02 in]DimensionsStack HeightStack Height5.2 mm[.205 in]Row-to-Row Spacing8.2 mm[.322 in]Usage ConditionsOperating Temperature Range-55 – 85 °C[-67 – 185 °F]Operation/ApplicationPower	PCB Mount Retention	With
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Housing MaterialHigh Temperature ThermoplasticHousing ColorBlackCenterline (Pitch).5 mm[.02 in]DimensionsStack Height5.2 mm[.205 in]Row-to-Row Spacing8.2 mm[.322 in]Usage ConditionsOperating Temperature Range-55 – 85 °C[-67 – 185 °F]Operation/ApplicationCircuit Application	Connector Mounting Type	Board Mount
Housing ColorBlackCenterline (Pitch).5 mm[.02 in]DimensionsStack Height5.2 mm[.205 in]Row-to-Row Spacing8.2 mm[.322 in]Usage ConditionsOperating Temperature RangeOperating Temperature Range-55 – 85 °C[-67 – 185 °F]Operation/ApplicationCircuit ApplicationPower	Housing Features	
Centerline (Pitch).5 mm[.02 in]DimensionsStack Height5.2 mm[.205 in]Row-to-Row Spacing8.2 mm[.322 in]Usage Conditions-55 – 85 °C[-67 – 185 °F]Operating Temperature Range-55 – 85 °C[-67 – 185 °F]Operation/Application-55 – 85 °C[-67 – 185 °F]Circuit ApplicationPower	Housing Material	High Temperature Thermoplastic
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Stack Height5.2 mm[.205 in]Row-to-Row Spacing8.2 mm[.322 in]Usage Conditions-55 – 85 °C[-67 – 185 °F]Operating Temperature Range-55 – 85 °C[-67 – 185 °F]Operation/Application-55 – 85 °C[-67 – 185 °F]Circuit ApplicationPower	Centerline (Pitch)	.5 mm[.02 in]
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Operating Temperature Range -55 – 85 °C[-67 – 185 °F] Operation/Application -55 – 85 °C[-67 – 185 °F] Circuit Application Power	Row-to-Row Spacing	8.2 mm[.322 in]
Operation/Application Circuit Application Power	Usage Conditions	
Circuit Application Power	Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
	Operation/Application	
Industry Standards	Circuit Application	Power
	Industry Standards	

SO DIMM Sockets, Small Outline (SO), Stack Height .205 in [5.2 mm], Right Angle Module Orientation, 200 / 260 Position, DDR4 DIMM



UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	800
Packaging Method	Tape & Reel
Product Compliance For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JAN 2021 (211) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not reviewed for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

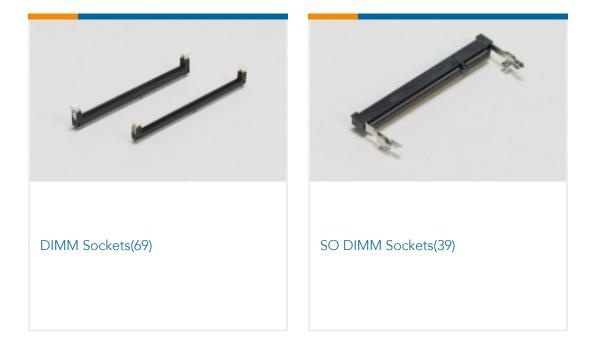
Compatible Parts



SO DIMM Sockets, Small Outline (SO), Stack Height .205 in [5.2 mm], Right Angle Module Orientation, 200 / 260 Position, DDR4 DIMM



Also in the Series DDR4 DIMM



Customers Also Bought



= TE	= TE	= TE	= TE	
TE Part #2118722-2	TE Part #2118725-2	TE Part #2118726-2	TE Part #5-2176362-1	
STD SHIELD FRAME, CRS-38.10X25.	STD SHIELD COVER, CRS-44.97X44.	STD SHIELD FRAME, CRS-44.37X44.	RQ 0402 133R 0.1% 10PPM 5K RL	
40X6.00MM	97X2.00MM	37X9.75MM		



Documents

Product Drawings DDR4 SODIMM 260P 5.2H RVS

English

CAD Files

3D PDF

3D

SO DIMM Sockets, Small Outline (SO), Stack Height .205 in [5.2 mm], Right Angle Module Orientation, 200 / 260 Position, DDR4 DIMM



Customer View Model

ENG_CVM_CVM_2309410-2_1.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2309410-2_1.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2309410-2_1.3d_stp.zip

English

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Product Specifications Application Specification

English